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(54) Title: DENSE VERTICALLY SEGMENTED SILICON COATING FOR LOW DEFECTIVITY IN HIGH-TEMPERATURE RAPID THERMAL PROCESSING

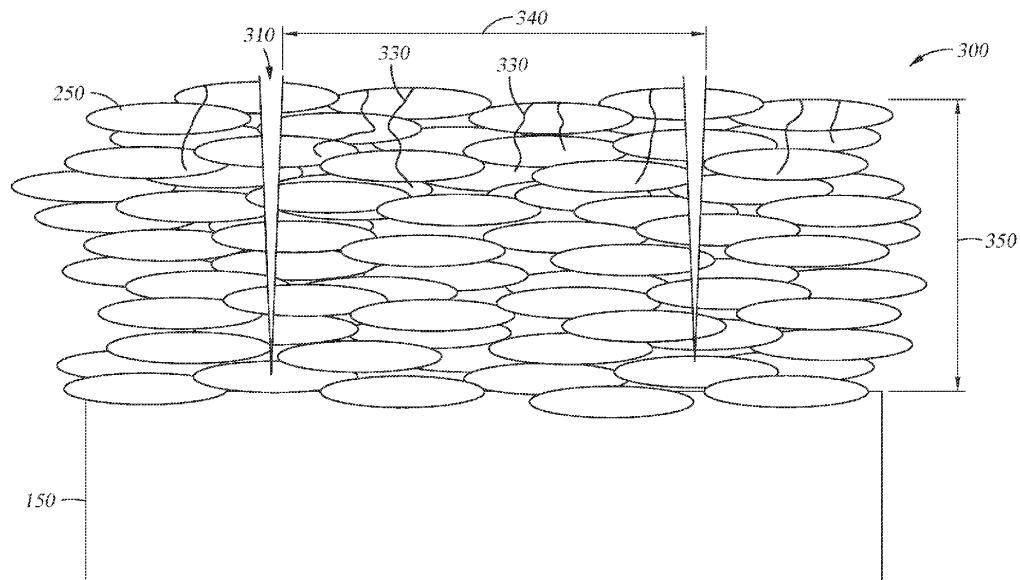


Fig. 3

(57) Abstract: This application generally relates to a chamber component for a thermal processing chamber comprising a base component having a coating disposed thereon, the coating having a base component having a coating disposed thereon, the coating includes a surface, a thickness, and a plurality of cracks extending from the surface of the coating through at least 40 percent of the thickness of the coating.

[Continued on next page]

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